Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**PAD FUNCTIONS:**

1. **1A**
2. **1B**
3. **1CLR**
4. **1Q**
5. **2Q**
6. **2CEXT**
7. **2REXT/CEXT**
8. **GND**
9. **2A**
10. **2B**
11. **2CLR**
12. **2Q**
13. **1Q**
14. **1CEXT**
15. **1REXT/CEXT**
16. **VCC**

**.068”**

**.060”**

**10 11 12 13 14**

**1**

**16**

**15**

**6 5 4 3 2**

**7**

**8**

**9**

**MASK**

**REF**

**LS**

**221**

**Top Material: Al**

 **Backside Material: Si**

**Bond Pad Size: .004” X .004”**

**Backside Potential: Ground**

**Mask Ref: LS 221**

**APPROVED BY: DK DIE SIZE .060” X .068” DATE: 8/29/22**

**MFG: TEXAS INSTRUMENTS THICKNESS .015” P/N: 54LS221**

**DG 10.1.2**

#### Rev B, 7/1